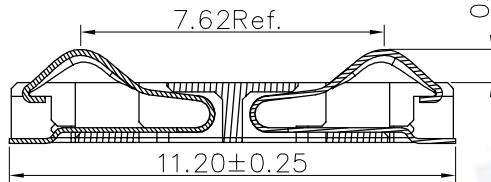
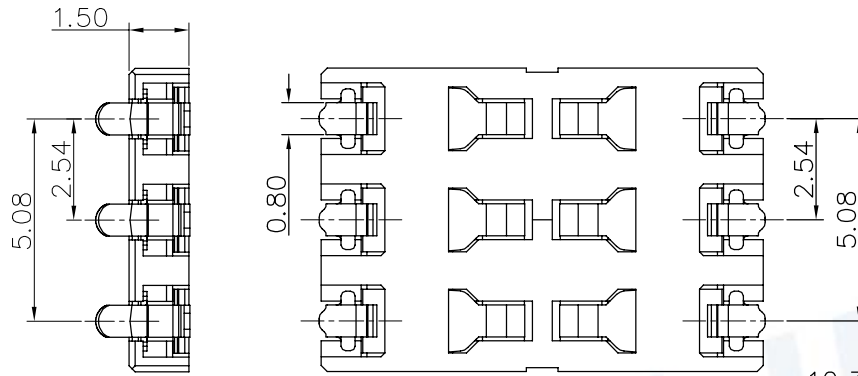
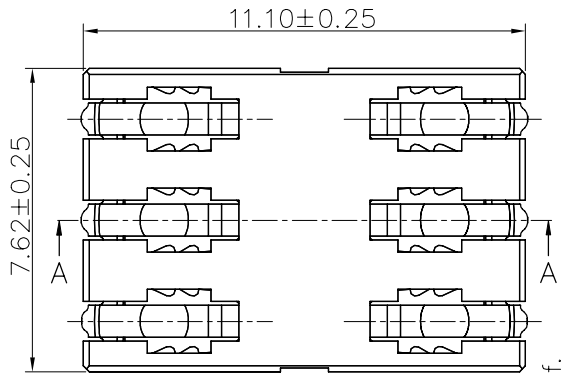
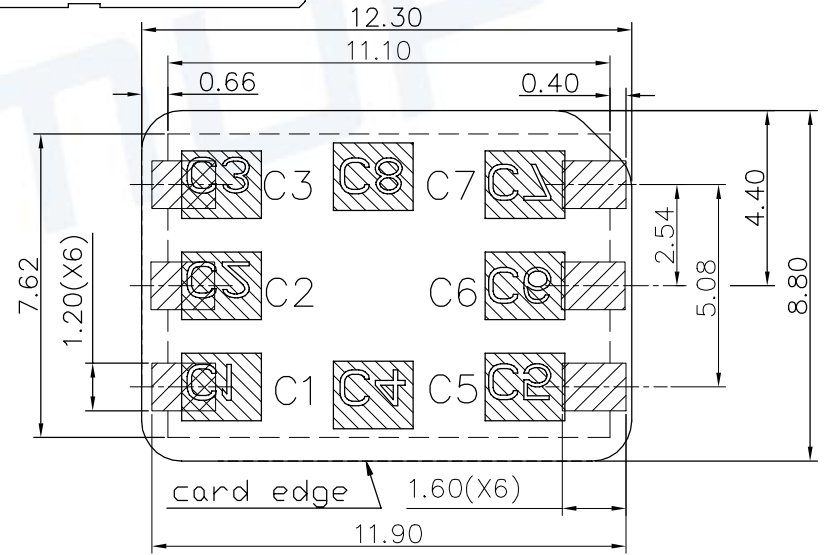
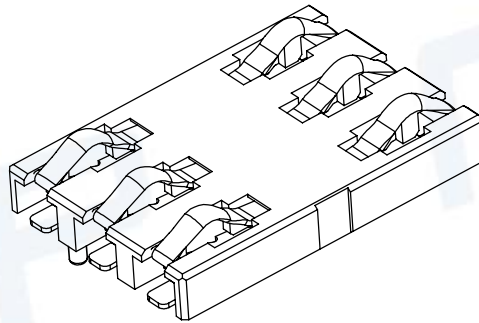


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Jul.20.2015
X2					



Section A-A



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions:11.1LX7.62WX1.50Hmm

Weight:Approx 0.40±0.1g

Durability:3,000 cycles min.

2.Electrical Characteristics

Contact resistance:

50mΩ typical 100mΩ max

Insulation resistance:

>1000MΩ/500V DC

3.Solderability

Vapor phase:215°C,30sec.Max

IR reflow:250°C,5sec.Max

Manual soldering:370°C,3sec.Max

4.Environmental Characteristics

Operating temperature:-40°C~+85°C

Operating humidity:10%~+95%RH

Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

MUP[®] MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP-C723-1**

TYPE: **H1.5 without post**

PROJ.	UNIT	SCALE	DRAWN	Henry Jul.20.2015	DWG NO.:
	mm	1:1	CHECKED	Henry Jul.20.2015	DWG-MUP-C723-1
CUSTOMER DRAWING			APPROVAL	Simon Jul.20.2015	SHEET
					1/1
					REVISION
					X1